Report NO.: MG00001000025

## 1. Product information

**Supplier :** JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

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|---|---|
| **Part Number :** | CJB120SN08 |
| **Package Type :** | TO-263-2L |

## 2. MATERIAL ANALYSIS DATA SHEET

| Material | Composition | CAS No. | % of weight | % of weight total |
|---|---|---|---|---|
| Wafer | Silicon | 7440-21-3 | 100.00% | 0.41% |
| Lead Frame | Iron | 7439-89-6 | 0.06% | 48.42% |
| | Phosphorus | 7723-14-0 | 0.04% | |
| | Copper | 7440-50-8 | 99.90% | |
| | Silver | 7440-22-4 | 0.01% | |
| Wire1 | aluminium | 7429-90-5 | 100.00% | 3.58% |
| Wire2 | Copper | 7440-50-8 | 100.00% | 0.57% |
| Soft Solder | Lead | 7439-92-1 | 92.50% | 3.01% |
| | Tin | 7440-31-5 | 5.00% | |
| | Silver | 7440-22-4 | 2.50% | |
| Mold Compound | Epoxy Resin A | Trade Secret | 7.12% | 30.40% |
| | Epoxy Resin B | 29690-82-2 | 4.91% | |
| | Phenol Resin | Trade Secret | 4.41% | |
| | Silica(Amorphous) A | 60676-86-0 | 74.68% | |
| | Silica(Amorphous) B | 7631-86-9 | 8.12% | |
| | Carbon Black | 1333-86-4 | 0.76% | |
| Plating | Tin | 7440-31-5 | 100.00% | 13.61% |